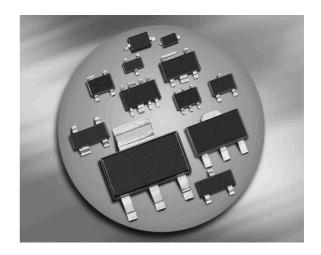


Silicon PIN Diode Array

- Surge protection device
- Designed for surge overvoltage clamping in antiparallel connection
- Pb-free (RoHS compliant) package





BAR66



Туре	Package	Configuration	L _S (nH)	Marking
BAR66	SOT23	series	1.8	PMs

Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_{R}	150	V
Forward current	I _F	200	mA
Total power dissipation	P _{tot}	250	mW
<i>T</i> _S ≤ 25 °C			
ESD contact discharge ¹⁾	V _{ESD}	25	kV
Peak pulse current ($t_p = 8 / 20 \mu s$) ²⁾	I_{pp}	12	Α
Junction temperature	T_{i}	150	°C
Operating temperature range	T_{op}	-55 125	
Storage temperature	$T_{ m stg}$	-55 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ³⁾ , BAR 66	R _{thJS}	≤ 290	K/W

1

 $^{^{1}}V_{\mbox{ESD}}$ according to IEC61000-4-2, only valid if pin 1 and pin 2 are connected

 $^{^2\}emph{I}_{\mbox{pp}}$ according to IEC61000-4-5, only valid if pin 1 and pin 2 are connected

 $^{^3}$ For calculation of R_{thJA} please refer to Application Note Thermal Resistance



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics	•	•		•	
Breakdown voltage	$V_{(BR)}$	150	-	-	V
$I_{(BR)} = 5 \mu A$, ,				
Reverse current	I _R	-	-	20	nA
V _R = 100 V					
Forward voltage	V_{F}	-	0.95	1.2	V
$I_{\rm F}$ = 50 mA					
Clamping voltage	V_{CL}				
$V_{\text{ESD}} = \pm 15 \text{ kV (contact)}^{1)}$		-	tbd	-	
$I_{PP} = 12 \text{ A}, t_p = 8/20 \ \mu\text{s}^{2}$		-	7	-	
AC Characteristics					
Diode capacitance	C _T				pF
$V_{R} = 35 \text{ V}, f = 1 \text{ MHz}$		-	0.4	0.6	
$V_{R} = 0 \text{ V}, f = 100 \text{ MHz}$		-	0.35	0.9	
Zero bias conductance	g_{P}	-	220	-	μS
$V_{R} = 0 \text{ V}, f = 1 \text{ GHz}$					
Forward resistance	r_{f}	-	1.5	1.8	Ω
$I_{\rm F}$ = 5 mA, f = 100 MHz					
Charge carrier life time	τ _{rr}	-	0.7	-	μs
$I_{\rm F}$ = 10 mA, $I_{\rm R}$ = 6 mA, measured at $I_{\rm R}$ = 3 mA,					
R_{L} = 100 Ω					

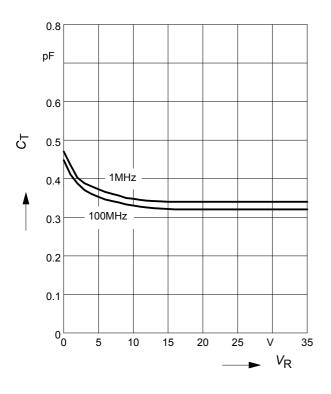
 $^{^{1}}V_{\mbox{ESD}}$ according to IEC61000-4-2, only valid if pin 1 and pin 2 are connected

 $^{^2\}emph{I}_{\mbox{pp}}$ according to IEC61000-4-5, only valid if pin 1 and pin 2 are connected



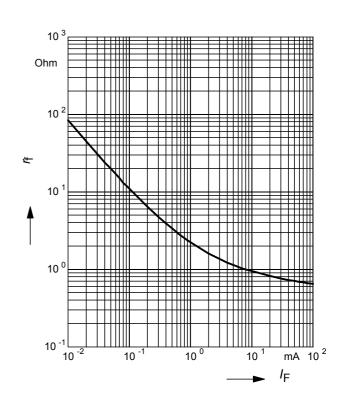
Diode capacitance $C_T = f(V_R)$

f = Parameter



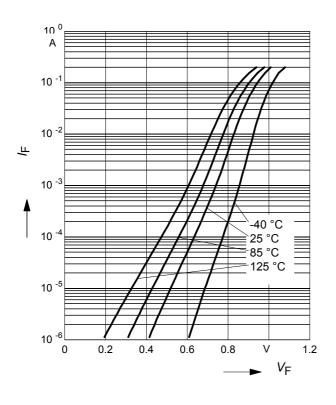
Forward resistance $r_f = f(I_F)$

f = 100MHz



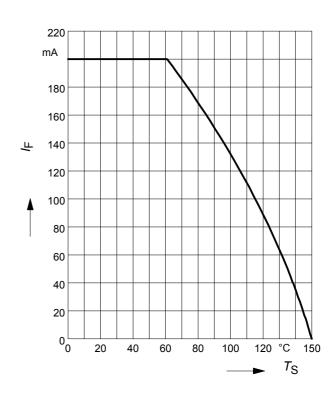
Forward current $I_F = f(V_F)$

 T_A = Parameter



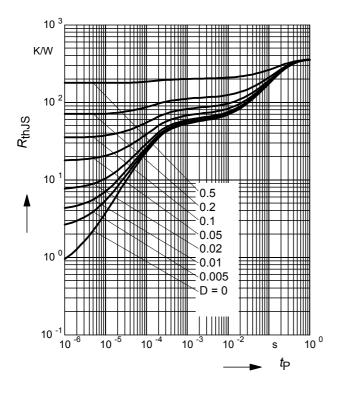
Forward current $I_F = f(T_S)$

BAR66





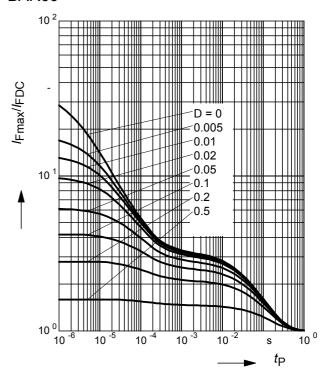
Permissible Puls Load $R_{thJS} = f(t_p)$ BAR66



Permissible Pulse Load

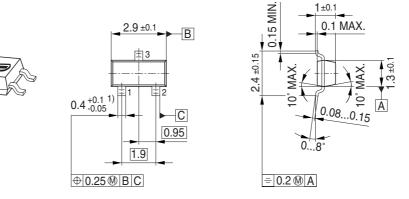
$$I_{\text{Fmax}}/I_{\text{FDC}} = f(t_{\text{p}})$$

BAR66



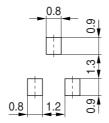


Package Outline

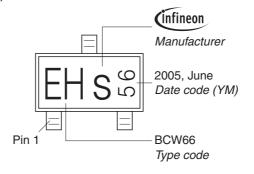


1) Lead width can be 0.6 max. in dambar area

Foot Print

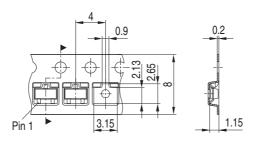


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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